List of Paten For Applicar Disclosure S (Use several	nt's Inf itateme	ormati nt	on	APPLICANT Akif Sultan et	al.	I hereby with the addresse	certify that the U.S. Postal S	nis corresponde	ence is being deposited	
				APPLICANT Akif Sultan et al.		CERTIFICATE OF MAILING 37 C.F.R. 1.8  I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450 op the date below:  May 21, 2604  Date  Timody Mytibheycutt				
					FILING DATE March 1, 2004		GROUP		٧ ٤	
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Information Disclosure Statement-PTO-1449 (Modified)